

Form **PTO-1595** U.S. DEPARTMENT OF COMMERCE SHEET U.S. Patent and Trademark Office (Rev. 03/01) 102741320 OMB No. 0651-0027 (exp. 5/31/2002) To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof 1. Name of conveying party(ies): 2. Name and address of receiving party(ies) John L. Caldwell Name: MICRON TECHNOLOGY, INC. Internal Address: Street Address: Additional name(s) of conveying party(ies) x No attached? Micron Technology, Inc. 3. Nature of Conveyance: 8000 S. Federal Way x Assignment Merger Security Agreement Change of Name City: Boise Other Zip: 83707-0006 State: ID Additional name(s) & Yes April 20, 2004 **Execution Date:** address(es) attached: 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the new application is: May 6, 2004 A. Patent Application No.(s): B. Patent No.(s): This application Additional numbers attached? 5. Name and address of party to whom correspondence Total number of applications and concerning document should be mailed: patents involved: Name: Thomas J. D'Amico DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP | 7. Total fee (37 CFR 3.41) 40.00 Internal Address: Atty. Dkt.: M4065.1017/P1017 **Enclosed** Street Address: Authorized to be charged to deposit account 2101 L Street NW Authorized to be charged to credit card (Form 2038 enclosed) 8. Deposit account number: City: State: Zip: 04-1073 Washington DC 20037-1526 (Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Thomas J. D'Amico May 6, 2004 Name of Person Signing Signature Date Total number of pages including cover sheet, attachments, and documents: 5/07/2004 SZEWDIE1 00000042 10839356 40.00 OP

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Docket No.: M4065.1017/P1017

## ASSIGNMENT AND AGREEMENT

For value received, I, John L. Caldwell, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled METHOD AND APPARATUS FOR IMAGER DIE PACKAGE QUALITY TESTING, described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

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PATENT REEL: 015303 FRAME: 0846

Docket No.: M4065.1017/P1017

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Date:

United States of A

State of County of

personally came

day of

John L. Caldwell

, to me known to be the individual

described in and who executed the foregoing instrument, and acknowledged execution

of the same.

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RECORDED: 05/06/2004

**PATENT** REEL: 015303 FRAME: 0847